POLYTRONICS
POLYTRONICS TECHNOLOGY CORP.

PRODUCT
DATASHEET

SMFF0603 Series Surface Mount Fuses Devices

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Description

Polytronics SMFF0603 series surface mount fast-acting fuse utilizes thick film process with extremely stable fusing element. The glass over coating can tolerate higher temperature profile, and the non-flammable ceramic substrate offers better heat conductivity and safety. SMFF0603 series is also RoHS compliant and halogen-free to meet global environmental standard.

Features

- Fast acting
- Compact size
- Thick film manufacturing method
- Ceramic substrate with silver fusing element
- Excellent environmental integrity

Application

- Battery pack
- Digital camera
- Game equipment
- Wireless base station
- LCD monitors and modules
- PC related equipment / peripherals
- Power supply
- Medical device

Agency Approval and Environmental Compliance

Agency	File Number
c UL us	UL/CSA: E331807

Regulation	Standard
RoHS	2011/65/EU
Halogen Free	IEC 61249-2-21:2003

Electrical Characteristics

Part Number	Marking	Current Rating (A)	Voltage Rating	Interrupting Rating	Typical Cold DCR† (Ω)	Typical I²T‡ (A²S)	Agency Approval c UL us
SMFF0603P050	F	0.5	32V DC	50A / 32V DC	0.785	0.0074	✓
SMFF0603P075	G	0.75			0.450	0.0251	✓
SMFF0603P100	H	1.0			0.210	0.0230	✓
SMFF0603P150	K	1.5			0.085	0.0473	✓
SMFF0603P200	N	2.0			0.047	0.0824	✓
SMFF0603P250	O	2.5			0.030	0.1313	✓
SMFF0603P300	P	3.0			0.025	0.1890	✓
SMFF0603P350	R	3.5			0.0215	0.2511	✓
SMFF0603P400	S	4.0	32V DC	35A / 32V DC	0.0160	0.3559	✓
SMFF0603P500	T	5.0			0.0107	0.7030	✓
SMFF0603P600	6	6.0			0.0095	1.5120	✓

† Measured at ≤ 10% rated current and 25°C
‡ Melting I²T at 10 times of rated current

♦ **Specifications are subject to change without notice.** ♦

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Electrical Specification

Ampere Rating	% of Current Rating	Opening Time
0.5A~6A	100%	4 Hours Min.
0.5A~0.75A	250%	20 Seconds Max.
1A~6A	250%	5 Seconds Max.
0.5A~6A	1000%	0.1 m Sec. Min.

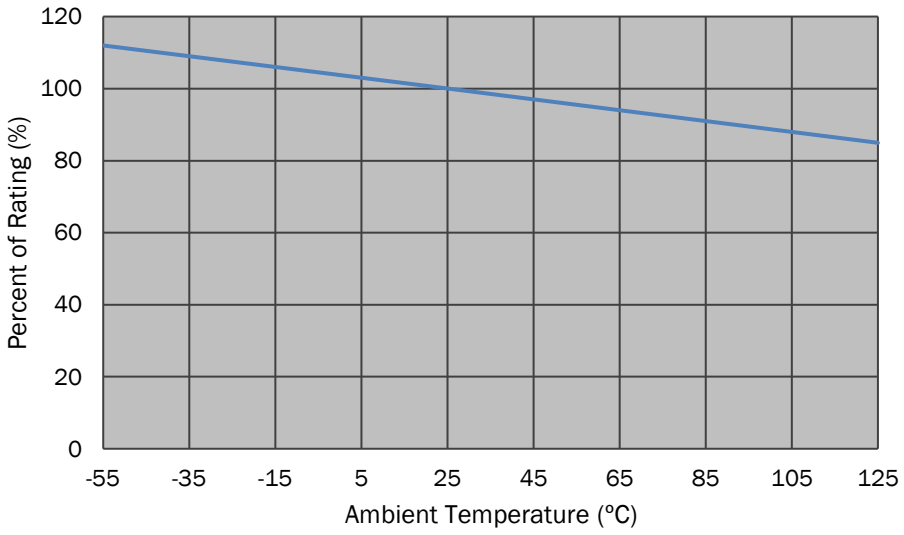
Physical Specifications

Materials	Substrate: Ceramic Terminations: Silver over-plated with 100% tin Element: Silver or Silver/palladium
Solderability	MIL-STD-202
Soldering Parameters	Wave Solder: 260°C, 10 seconds max. Reflow Solder: 260°C, 20 seconds max. Hand Solder: 350°C, 5 seconds max.

Environmental Specifications

Operating Temperature	-55°C to 125°C
Moisture Sensitivity Level	Level 1, JEDEC J-STD-020F

Thermal Derating Curve



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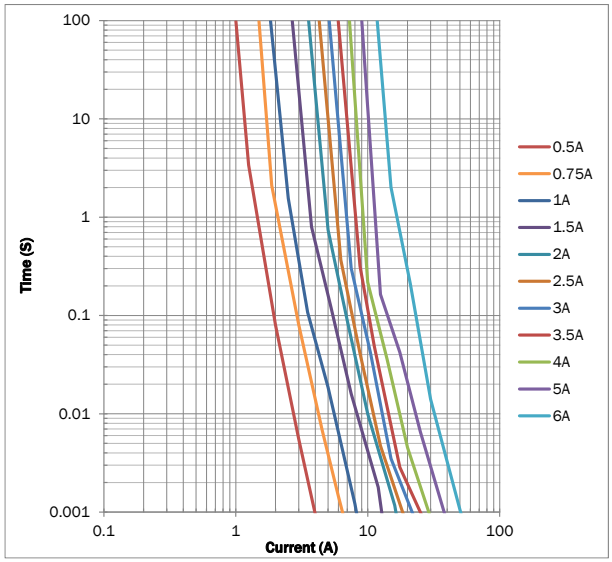
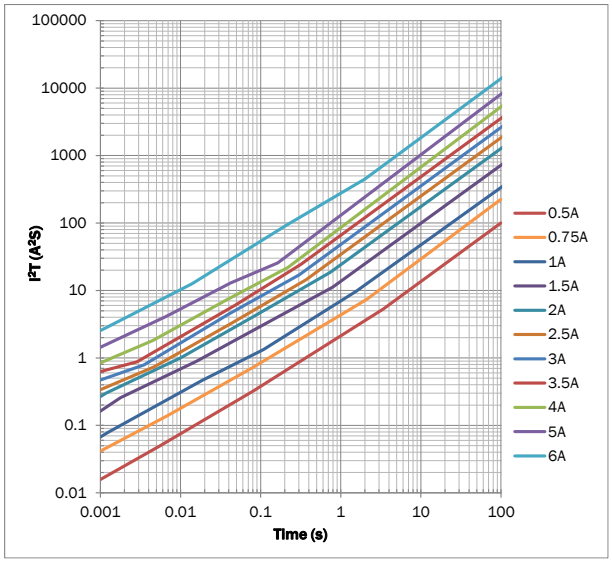
Time-Current Curve



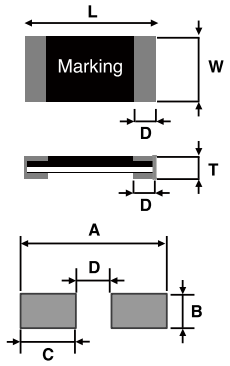
I²T vs Time Curve



Physical Dimensions (mm.)

Dimensions (mm)

L	W	T	D
1.60±0.15	0.80±0.15	0.40±0.10	0.30±0.20



Recommended Solder Pad Dimension (mm)

A	B	C	D
2.05±0.05	1.2±0.10	0.6±0.10	0.85±0.05

Dimensionsof Standard Test Board (mm)

Ampere Rating	Board Thickness	Copper Layer Thickness	Copper Trace Width
1A~6A	1.6	0.035	5.0

Part Number System

SMF F 0603 P □□□

- Current Rating in 100X Ampere
- Polytronics Symbol
- Device Dimension in 1/100 inch
- Series, F=Fast-Acting, S=Slow-Blow
- Surface-Mount Fuse

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Reliability Test

Characteristics	Test condition / Methods	Requirement	Test Reference
Time/Current	100% In	No Fusing, 4 hours min.	UL 248-14
	250% In (0.5A~0.75A) 250% In (1A~6A)	≤ 20 sec. ≤ 5 sec.	Refer to Spec
	1000% In	> 0.1 msec.	
Voltage Drop	100% In	Deviation between the mean value: <15%	IEC 60127-4
Endurance Test	100% In, 1hour on, 15min off, 100cycles; then followed by 1hour at 125% In	|ΔR|<10%	IEC60127-4
Temperature Rise	100% In	|ΔT|: <75°C	IEC 60127-4
Interrupting Ability	50A/32V DC (1A~3.5A) 35A/32V DC (4A~6A)	Without permanent arcing, ignition, and bursting of fuse link	UL 248-14 IEC 60127-4
Solderability	240°C ± 5°C, 3sec ± 0.5sec	95% coverage min.	IEC 60127-4 MIL-STD-202 Method208
Resistance to Soldering	260°C ± 5°C, 10sec ± 0.5sec	|ΔR|: <10% Legible appearance	MIL-STD-202 Method210
Bending Test	Distance between holding points: 90mm Bending: 1 mm; Time: 10 sec	|ΔR|: <10% No mechanical damages	IEC 60127-4
High Temperature Operating Life	70°C ± 2°C at 60% In for 96 hours	|ΔR|: <10%; No fusing	MIL-STD-202 Method 108
Low Temperature Storage	-55°C ± 3°C for 96 hours	|ΔR|: <10%	IEC 60068-2-1
High Temperature Storage	125°C ± 2°C for 96 hours	|ΔR|: <10%	IEC 60068-2-2
Humidity (Steady State)	40°C ± 2°C, 90~95%RH for 1000 hours	|ΔR|: <10%	MIL-STD-202 Method 103
Salt Spray	5% salt solution, 48 hours exposure	|ΔR|: <10% Legible appearance	MIL-STD-202 Method 101
Thermal Shock	100 cycles between -65°C /+125°C 60 minutes at each extreme zone	|ΔR|: <10% No mechanical damage	MIL-STD-202 Method 107

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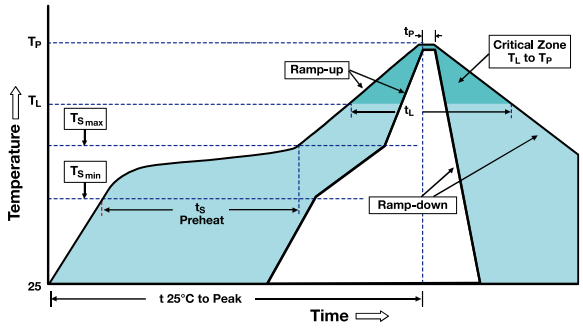
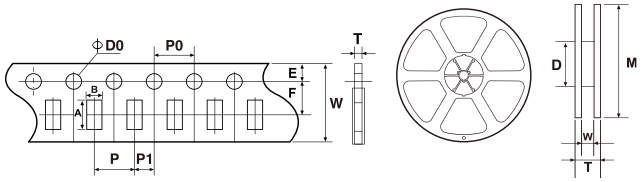
Soldering Parameters



Average Ramp-Up Rate (Ts_{max} to T_P)	3°C/second max.
Preheat	
-Temperature Min (Ts_{min})	150°C
-Temperature Max (Ts_{max})	200°C
-Time (Ts_{min} to Ts_{max})	60-120 seconds
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20 seconds
Ramp-Down Rate	6°C /second max.
Time 25°C to Peak Temperature	8 minutes max.

Note 1: All temperature refer to topside of the package, measured on the package body surface.
Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Tape & Reel Specification (mm.)



A	1.85 ± 0.10
B	1.10 ± 0.10
W	8.00 ± 0.20
F	3.50 ± 0.05
E	1.75 ± 0.10
P	4.00 ± 0.10
P0	4.00 ± 0.10
P1	2.00 ± 0.10
D0	Ø 1.50 ± 0.10
T	0.60 ± 0.10

M	Ø 178.0 ± 2.0
W	9.5 ± 1.0
T	12.5 ± 1.5
A	2.0 ± 0.5
B	Ø 13.0 ± 0.5
C	Ø 21.0 ± 0.5
D	Ø 58.0 ± 2.0

Packaging Quantity

Part Number	Tape & Reel Quantity
SMFF0603PXXX	5000

Storage

- The ambient temperature recommended for storage shall be between 5°C ~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Fuse product is not recommended for any type of coating. Polytronics is not responsible for any damage directly or indirectly related to the coating.
- For copper layer thickness or copper trace width different from the standard test board, fusing characteristics needs to be verified to ensure product performance meet user requirement.